

China Fan-out Wafer Level Packaging Market Research Report 2018

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Abstracts

The global Fan-out Wafer Level Packaging market is valued at XX million USD in 2017 and is expected to reach XX million USD by the end of 2025, growing at a CAGR of XX% between 2017 and 2025.

China plays an important role in global market, with market size of xx million USD in 2017 and will be xx million USD in 2025, with a CAGR of xx%.

This report studies the Fan-out Wafer Level Packaging development status and future trend in China, focuses on top players in China, also splits Fan-out Wafer Level Packaging by type and by applications, to fully and deeply research and reveal the market general situation and future forecast.

The major players in China market include

STATS ChipPAC

TSMC

Texas Instruments

Rudolph Technologies

SEMES

SUSS MicroTec

STMicroelectronics

Ultratech

Geographically, this report splits the China market into six regions,

South China

East China

Southwest China

Northeast China

North China

Central China

Northwest China

On the basis of product, this report displays the sales volume (K Units), revenue (Million USD), product price (USD/Unit), market share and growth rate of each type, primarily split into

Bump Pitch 0.4mm

Bump Pitch 0.35mm

Others

On the basis of the end users/application, this report covers

Analog and Mixed IC

Wireless Connectivity

Misc, Logic and Memory IC

MEMS and Sensors

CMOS Image Sensors

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